

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Masanobu IKEDA</td> <td>11/27/2008</td> </tr> <tr> <td>Ryoichi ITO</td> <td>11/27/2008</td> </tr> <tr> <td>Daisuke TAKAMA</td> <td>11/27/2008</td> </tr> <tr> <td>Kenta SEKI</td> <td>11/27/2008</td> </tr> <tr> <td>Natsuki OTANI</td> <td>12/01/2008</td> </tr> </tbody> </table>		Name	Execution Date	Masanobu IKEDA	11/27/2008	Ryoichi ITO	11/27/2008	Daisuke TAKAMA	11/27/2008	Kenta SEKI	11/27/2008	Natsuki OTANI	12/01/2008
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RECEIVING PARTY DATA													
Name:	SONY CORPORATION												
Street Address:	1-7-1 Konan												
Internal Address:	Minato-ku												
City:	Tokyo												
State/Country:	JAPAN												
PROPERTY NUMBERS Total: 1													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12331262</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12331262								
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CORRESPONDENCE DATA													
Fax Number:	(312)441-0570												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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Email:	dayala@rdlklaw.com												
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Address Line 4:	Chicago, ILLINOIS 60606												
ATTORNEY DOCKET NUMBER:	075834.01194												
NAME OF SUBMITTER:	Robert J. Depke												

CH \$40.00 12331262

Total Attachments: 2

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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
DISPLAY

_____ for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____

This assignment executed on the dates indicated below.

Masanobu IKEDA

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Masanobu Ikeda

27th Nov. 2008

Signature of first or sole inventor

Date of this assignment

Ryoichi ITO
 Name of second inventor Execution date of U.S. Patent Application
Kanagawa, Japan
 Residence of second inventor
Ryoichi Ito 27th Nov. 2008
 Signature of second inventor Date of this assignment

Daisuke TAKAMA
 Name of third inventor Execution date of U.S. Patent Application
Kanagawa, Japan
 Residence of third inventor
Daisuke Takama November 27, 2008
 Signature of third inventor Date of this assignment

Kenta SEKI
 Name of fourth inventor Execution date of U.S. Patent Application
Kanagawa, Japan
 Residence of fourth inventor
Kenta Seki November 27, 2008
 Signature of fourth inventor Date of this assignment

Natsuki OTANI
 Name of fifth inventor Execution date of U.S. Patent Application
Kanagawa, Japan
 Residence of fifth inventor
Natsuki Otani December 1, 2008
 Signature of fifth inventor Date of this assignment